

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.37508	100.0	4
Subtotal				0.37508	100	4
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0376	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01128	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.0376	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.51481	99.77	400.0777
Subtotal				37.60129	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84907	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.93557	10.0	63.3
	Filler	Silica fused	60676-86-0	50.45231	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11871	0.2	1.266
Subtotal				59.35566	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34422	100.0	25
Subtotal				2.34422	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01398	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.04723	100.0	0.50364
Subtotal				0.06121	200	0.65274
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00525	2.0	0.056
	Lead alloy	Silver (Ag)	7440-22-4	0.00656	2.5	0.07
	Lead alloy	Lead (Pb)	7439-92-1	0.25074	95.5	2.674
Subtotal				0.26255	100	2.8
Total				100.00001	100	1066.45274

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